ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pa	IPC. Bannock	burn, Illinois, A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration er	on of the sub compasses	bstances w all lower	vithin the manufactu level materials for w	rer listed i hich the r	tem. Note: nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
			Form Type Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informati					tion					
upplier Information														
Company name* Company			ny unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2025-05-11				
ntact Name Title - Contact					Phone - Contact*				Email - Contact*					
Product-Env-Stewards Product Enviro Co			o Compliance		NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Represen			entative		Phone - Representative*			Email - Representative*						
Product-Env-Stewards Produc			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	ester Item Number Mfr Item Num		Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	NSM40	NSM4002MR6T1G Dual NPN Transis		tors		2025-05-11		Cl	CN1		13.43	mg	Each	
Ianufacturing Proccess Informa	ition		•			•	-							
Terminal Plating / Grid Array M	aterial	al Terminal Base Alloy J-		J-STD-020 MS	L Rating	Peak Process Body		y Temperature Max Time at Peak		Tempera	ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secor	nds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	dering is 10-3	0 seconds											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).				-	_		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Lead Frame	2.55	mg	В	Nickel (Ni)	7440-02-0		0.9664	mg
			Supplier	Iron (Fe)	7439-89-6		1.3362	mg
			Supplier	Copper (Cu)	7440-50-8		0.2473	mg
Mold Compound-Black	10.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		1	mg
			Supplier	Carbon Black (C)	1333-86-4		0.05	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.45	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.5	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1	mg
Plating	0.13	mg	Supplier	Tin (Sn)	7440-31-5		0.13	mg
Wire Bond - Cu	0.08	mg	Supplier	Copper (Cu)	7440-50-8		0.08	mg